

HDMI A S1V 1.9N1 RL**Weidmüller Interface GmbH & Co. KG**

Klingenbergstraße 26

D-32758 Detmold

Germany

www.weidmueller.com**HDMI sockets for PCBs - reliable connectivity for your electronics projects**

HDMI sockets from Weidmüller offer a high-quality solution for the transmission of video, audio and Ethernet signals (HEC) in industrial applications

Features and benefits:

- Compact design: Ideal for space-saving PCB designs thanks to various outlet directions
- High data transmission rate: Supports HDMI 2.0 and 4K resolutions and Ethernet up to 100 Mbit/s
- Easy integration: Standardized design facilitates mounting and integration into the device
- EMC protection: Reliable protection against interference for clean data transmission
- Perfectly suited for processing in automated SMT processes thanks to tape-on-reel packaging
- Durability: Robust design ensures a reliability in demanding environments

General ordering data

Version	, female header, SMD solder connection, 0.50 mm, Number of poles: 5, 180°, Gold over nickel, black, Tape
Order No.	3107660000
Type	HDMI A S1V 1.9N1 RL
GTIN (EAN)	4099987174633
Qty.	1,600 pc(s).
Packaging	Tape

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Technical data

Dimensions and weights

Depth	6.2 mm	Depth (inches)	0.244 inch
Height	15 mm	Height (inches)	0.591 inch
Width	15 mm	Width (inches)	0.591 inch
Net weight	0.006 g		

System specifications

LED	No	Model	Socket connector
Mounting onto the PCB	SMD solder connection	Number of poles	5
Number of solder pins per pole	1	Outgoing elbow	180°
Performance-Category	100 MBit/s	Pitch in inches (P)	0.02 "
Pitch in mm (P)	0.5 mm	Plugging cycles	≥ 10000
Plugging force/pole, max.	35 N	Protection degree	IP20
Pulling force / pole, min.	10 N	Shield surface	nickel-plated
Shielding	Yes, 360° shield contact	Shielding material	Stainless steel
Solder pin dimensions	Octagonal	Soldering process	Reflow soldering, Manual soldering
Transmission rate	100 MBit/s	Type of connection	Socket connector

Electrical properties

Dielectric strength, contact / contact	500 V AC / 1 min	Insulation strength	≥ 100 MΩ
Volume resistance	≤10 mΩ		

Material data

Insulating material	LCP	Colour	black
Colour chart (similar)	RAL 9011	Insulation strength	≥ 100 MΩ
Moisture Level (MSL)	1	UL 94 flammability rating	V-0
Contact base material	Copper alloy	Contact material	Cu-alloy
Contact surface	Gold over nickel	Layer structure of plug contact	≤ 1 μ" Au
Storage temperature, min.	-20 °C	Storage temperature, max.	65 °C
Operating temperature, min.	-20 °C	Operating temperature, max.	65 °C

Packing

Packaging	Tape	VPE length	0 mm
VPE width	0 mm	VPE height	0 mm

Classifications

ETIM 6.0	EC002637	ETIM 7.0	EC002637
ETIM 8.0	EC002637	ETIM 9.0	EC002637
ETIM 10.0	EC002637	ECLASS 9.0	27-44-04-02
ECLASS 9.1	27-44-04-02	ECLASS 10.0	27-44-04-02
ECLASS 11.0	27-46-02-01	ECLASS 12.0	27-46-02-01
ECLASS 13.0	27-46-02-01	ECLASS 14.0	27-46-02-01
ECLASS 15.0	27-46-02-01		

Environmental Product Compliance

RoHS Compliance Status	Compliant without exemption
REACH SVHC	No SVHC above 0.1 wt%

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ROHS

Conform

Downloads

Engineering Data

[CAD data – STEP](#)

Technical Documentation

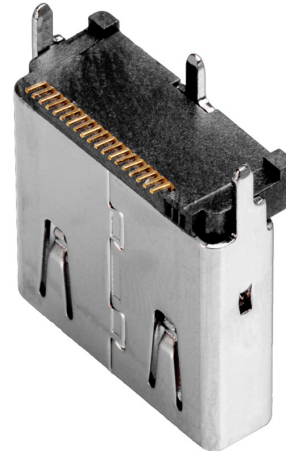
[3107660000 HDMI A S1V 1.9N1 RL 20241127](#)

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Drawings



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Drawings



Recommended reflow soldering profile

Weidmüller Interface GmbH & Co. KG

Klingenbergstraße 16

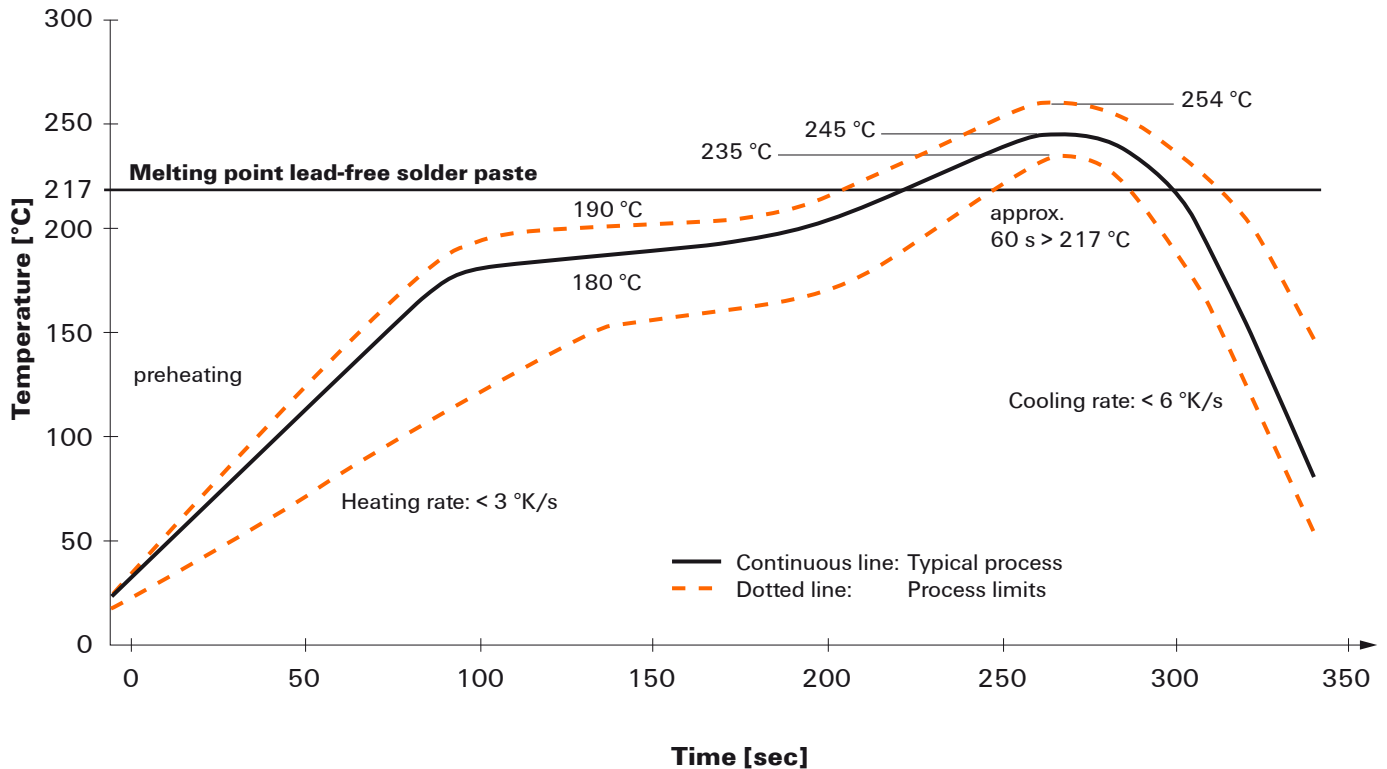
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Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically $\leq +3\text{K/s}$. In parallel the solder paste is 'activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at $\geq -6\text{K/s}$ solder is cured. Board and components cool down while avoiding cold cracks.